PART INFORMATION	
Mfg Item Number	MPXAZ6115AP
Mfg Item Name	SENSOR 8PIN GP

SUPPLIER	
Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2016-03-17
Response Document ID	0848K50010S289A1.22
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
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Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION	
EU RoHS	Yes
Pb Free	No
HalogenFree	No
Plating Indicator	
EU RoHS Exemption(s)	7c-I

MANUFACTURING	
Mfg Item Number	MPXAZ6115AP
Mfg Item Name	SENSOR 8PIN GP
Version	ALL
Weight	1.791900
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s),the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
Exemptions in this part	7c-I:Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight 6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight 6(c) : Copper alloy containing up to 4% lead by weight 7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead) 7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications 7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound 7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher 7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC 7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors 15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%		ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.002						g					
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Silicone gum	67762-94-1		0.00002065	g	10324	1.0324		11	0.0011
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and Silicones, di-Me, Me vinyl, vinyl group-terminated	68083-18-1		0.00024582	g	122911	12.2911		137	0.0137
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.00078662	g	393313	39.3313		438	0.0438
Non-Conductive Epoxy/Adhesive		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.00044248	g	221239	22.1239		246	0.0246
Non-Conductive Epoxy/Adhesive		Glass	D4 and HMDZ treated Silicon Dioxide	68937-51-9		0.00029499	g	147493	14.7493		164	0.0164
Non-Conductive Epoxy/Adhesive		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.00018682	g	93412	9.3412		104	0.0104
Non-Conductive Epoxy/Adhesive		Metals	Titanium (IV) Oxide	13463-67-7		0.00002262	g	11308	1.1308		12	0.0012
Port	0.6882						g					
Port		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.41013967	g	595960	59.596		228885	22.8885
Port		Glass	Proprietary Material-Other glass compounds (without lead, chromium, cadmium or mercury)	-		0.27806033	g	404040	40.404		155176	15.5176
Copper Lead Frame	0.796						g					
Copper Lead Frame		Metals	Copper, metal	7440-50-8		0.43906722	g	551592	55.1592		245047	24.5047
Copper Lead Frame		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0168545	g	21174	2.1174		9405	0.9405
Copper Lead Frame		Metals	Gold, metal	7440-57-5		0.00062964	g	791	0.0791		351	0.0351
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00037014	g	465	0.0465		206	0.0206
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.01058362	g	13296	1.3296		5906	0.5906
Copper Lead Frame		Nickel (external applications only)	Nickel	7440-02-0		0.00662511	g	8323	0.8323		3697	0.3697
Copper Lead Frame		Metals	Palladium, metal	7440-05-3		0.00032477	g	408	0.0408		181	0.0181
Copper Lead Frame		Plastics/polymers	Polyphenylene Sulfide (PPS)	26125-40-6		0.10136344	g	127341	12.7341		56567	5.6567
Copper Lead Frame		Glass	Fibrous-glass-wool	65997-17-3		0.21961958	g	275904	27.5904		122562	12.2562
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.00056198	g	706	0.0706		313	0.0313
Bonding Agent	0.0207						g					
Bonding Agent		Metals	Proprietary Material-Other aluminum compounds	-		0.009315	g	450000	45		5198	0.5198
Bonding Agent		Solvents, additives, and other materials	Other guanidine compounds	-		0.0005175	g	25000	2.5		288	0.0288
Bonding Agent		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.0005175	g	25000	2.5		288	0.0288
Bonding Agent		Plastics/polymers	Other phenolic resins	-		0.01035	g	500000	50		5775	0.5775
Pb Glass Frit Semiconductor Di	0.0145				7c-I		g					
Pb Glass Frit Semiconductor Di		Lead/Lead Compounds	Lead (II) titanate	12060-00-3		0.00015052	g	10381	1.0381		84	0.0084
Pb Glass Frit Semiconductor Di		Glass	Fibrous-glass-wool	65997-17-3		0.00014417	g	9943	0.9943		80	0.008
Pb Glass Frit Semiconductor Di		Solvents, additives, and other materials	2,2,4-trimethyl-1,3-pentanediol-1-monoisobutyrate	25265-77-4		0.00014417	g	9943	0.9943		80	0.008
Pb Glass Frit Semiconductor Di		Glass	Silicon, doped	-		0.01406114	g	969733	96.9733		7847	0.7847
Gel Die Encapsulant	0.0368						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.028704	g	780000	78		16018	1.6018
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.008096	g	220000	22		4518	0.4518
Gel Die Encapsulant	0.0368						g					
Gel Die Encapsulant		Solvents, additives, and other materials	Fluorosilicone monomer (fluorosilicone rubber)	2374-14-3		0.028704	g	780000	78		16018	1.6018
Gel Die Encapsulant		Plastics/polymers	Oxetane, 2,2,3,3-tetrafluoro-homopolymer, fluorinated	113114-19-5		0.008096	g	220000	22		4518	0.4518
Bonding Wire	0.0011						g					
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0011	g	1000000	100		613	0.0613
Cap/Cover	0.1958						g					
Cap/Cover		Metals	Chromium, metal	7440-47-3		0.03608007	g	184270	18.427		20135	2.0135
Cap/Cover		Metals	Copper, metal	7440-50-8		0.00049028	g	2504	0.2504		273	0.0273
Cap/Cover		Solvents, additives, and other materials	Sulfur	7704-34-9		0.00000979	g	50	0.005		5	0.0005
Cap/Cover		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00003427	g	175	0.0175		19	0.0019
Cap/Cover		Solvents, additives, and other materials	Silicon	7440-21-3		0.00098037	g	5007	0.5007		547	0.0547
Cap/Cover		Metals	Iron, metal	7439-89-6		0.13918971	g	710877	71.0877		77677	7.7677
Cap/Cover		Metals	Manganese, metal	7439-96-5		0.00225503	g	11517	1.1517		1258	0.1258
Cap/Cover		Nickel (external applications only)	Nickel	7440-02-0		0.01647128	g	84123	8.4123		9192	0.9192
Cap/Cover		Metals	Titanium, metal	7440-32-6		0.000196	g	1001	0.1001		109	0.0109
Cap/Cover		Solvents, additives, and other materials	Carbon	7440-44-0		0.0000932	g	476	0.0476		52	0.0052

LINKS	
MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcds/MPXAZ6115AP_IPC1752_v11.xml

http://www.freescale.com/mcds/MPXAZ6115AP_IPC1752A.xml